

## MDA STTR FY10 (09.B) Phase I Selections - By Firm

Firm Name	Topic Number	Proposal Title
Anokiwave, Inc.	MDA09-T004	Low Cost, High Performance Transmit/Receive Integrated Circuits on a single chip
Applied Physical Electronics, L.C.	MDA09-T010	Novel Directed Energy Options in Ballistic Missile Defense
Applied Radar, Inc.	MDA09-T003	Software Defined Wideband DREX Receiver
ASR Corporation	MDA09-T010	Novel Directed Energy Options in Ballistic Missile Defense
CFD Research Corporation	MDA09-T005	Multi Junction Solar cells for Satellite
Creare Inc.	MDA09-T007	An Efficient 35 K Cryocooler Driven by Electrochemical Compressors
DGNSS Solutions, LLC	MDA09-T003	Software Defined Multi-Channel Radar Receivers for X-band Radars
EPIR Technologies Inc	MDA09-T007	Low Temperature Thermoelectric Cooling of Infrared Focal Plane Arrays with HgCdTe-based Superlattices
Exothermics, Inc.	MDA09-T002	Ultrahigh Temperature Materials for Missile Defense Propulsion and Aerothermal Applications
Gloyer-Taylor Laboratories LLC	MDA09-T009	UCDS Unsteady Reaction Model
IllinoisRocstar LLC	MDA09-T009	High-Fidelity Multiphysics Simulations of Nozzle Erosion
Inlustra Technologies, Inc.	MDA09-T001	Producibility of Gallium Nitride Semiconductor Materials
Kyma Technologies, Inc.	MDA09-T001	In-Situ Monitoring during HVPE for the Producibility of Semi-Insulating GaN
MaXentric Technologies LLC	MDA09-T003	Software Defined Multi-Channel Radar Receivers for X-band Radars
Metacomp Technologies, Inc.	MDA09-T009	Propulsion Modeling
Noisefigure Research LLC	MDA09-T004	Low Cost, High Performance Transmit/Receive Integrated Circuits on a single chip
Plasma Processes, Inc.	MDA09-T002	An Ultra-High Temperature Ceramic with Improved Fracture Toughness and Oxidation Resistance
RNET Technologies, Inc.	MDA09-T006	Development for Radiation Hardened Applications of Advanced Electronics Materials, Processes, and Devices
Sensor Electronic Technology, Inc.	MDA09-T001	AlInN/GaN HFET over Free-Standing bulk GaN substrates
Sinmat Inc	MDA09-T001	Contamination-free, Ultra-rapid Reactive Chemical Mechanical Polishing (RCMP) of GaN substrates
Spire Semiconductor, LLC	MDA09-T005	Low Cost Multi Junction Solar Cells for Space Applications Incorporating Quantum Wells Sub Cells
UES, Inc.	MDA09-T002	Fabrication of Ta-Hf-C-based Ultra High Temperature Composites via a
United Silicon Carbide, Inc	MDA09-T006	Development for Radiation Hardened Advanced Electronic Circuits
Utron Kinetics, LLC	MDA09-T002	Rapid Combustion Driven High Pressure Powder Compaction of Refractory Alloys and Dispersion Strengthened Composites for High Temperature Applications
Versaq	MDA09-T004	Low Cost, High Performance Transmit/Receive Integrated Circuits on a Single Chip